



## **CyberOptics Launches Next-Generation Airborne Particle Sensor Technology for Greater Precision and Versatility**

***Company to also Feature All-in-one Sensor That Saves Time and Expenses While Improving Yields***

**Dresden, Germany** —October 6th, 2015— [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, debuts its next-generation Airborne Particle Sensor (APS) technology, APS2, in both WaferSense® and ReticleSense® form factors at [SEMICON Europa](#), Oct. 6-8, 2015 in Booth #1124. Now, the technology is even more sensitive, accurate and versatile.

CyberOptics' Airborne Particle Sensors improve equipment set-up and long-term yields in semiconductor fabs by wireless monitoring airborne particles in real-time. This next-generation APS2 enables:

- Better Accuracy: An 80% improvement with 5 vs. 25 false counts/hour
- Increased Sensitivity: Measurement of even smaller particles down to .14 microns
- Greater Versatility: Thinner and lighter form factor travels through virtually all tools

“The technology enables even greater precision,” said Dr. Subodh Kulkarni, president and chief executive officer, CyberOptics. “We’re delivering even more value to the semiconductor fabs and OEMs by advancing a technology that they have relied upon to save time, save expense and improve yields.”

The new APS2 quickly monitors, identifies and enables troubleshooting of airborne particles down to .14um within semiconductor process equipment and automated material handling systems. CyberOptics APS2 technology easily identifies when and where the particles originate and speeds equipment qualification with wireless measurements, shortens equipment maintenance cycles with wafer-like and reticle form factors and lowers equipment expenses by providing objective and reproducible data.

At the SEMICON Europa show, CyberOptics will also demonstrate its new WaferSense and ReticleSense Auto Multi Sensors (AMS/AMSR) that measure leveling, vibration and humidity in an all-in-one wireless real-time device. With its thin and light form factor, the AMS travels through virtually any tool and the AMSR can capture multiple measurements in all locations of the reticle environment. The all-in-one devices are yet another way to increase yield and reduce downtime in semiconductor environments.

### **About the CyberOptic WaferSense and ReticleSense Line**

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS), the Airborne Particle

Sensor (APS), the next-generation Airborne Particle Sensor (APS2) and the new Auto Multi Sensor (AMS) are available in various wafer shaped form factors depending on the device, including 150mm, 200mm, 300mm and 450mm wafer sizes. The ReticleSense measurement portfolio including the Airborne Particle Sensor (APSR & APSRQ) and next-generation APS2, the Auto Leveling System (ALSR) and the new Auto Multi Sensor (AMSR) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit the company's website at [www.cyberoptics.com](http://www.cyberoptics.com).

### **About CyberOptics**

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; expectations regarding LDI and its impact on our operations; integration risks associated with LDI and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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